



- NOTES:
- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0. COLOR:NATURAL.
 - CONTACT: COPPER ALLOY.
 - FINISH:
 - CONTACT:
 - 50~100u" NICKEL UNDERPLATING OVERALL. CONTACT AREA: GOLD 15u" MIN SOLDER TAIL: GOLD 1u" MIN
 - 2:50~100u" NICKEL UNDERPLATING OVERALL. CONTACT AREA: GOLD FLASH OVERALL SOLDER TAIL: GOLD FLASH OVERALL
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - SPEC.PLS REFER TO PS-51210-XXXXX-XXX
 - PART NUMBER

51209-XXX X X-XXX

CKTS	XXX	LOGO	DIMG
PACKING	001	ACES	3.50
	003	ACES	2.10

PLATING
 C:CONTACT AREA: GOLD 15u" MIN
 SOLDER TAIL: GOLD 1u" MIN
 2:GOLD FLASH OVERALL

CKTS	DIMA	DIMB	DIMC	DIMD	DIME	DIMF
007	16.00	14.74	13.58	12.00	11.10	10.00
010	22.00	20.74	19.58	18.00	17.10	16.00
012	26.00	24.74	23.58	22.00	21.10	20.00

QUALITY SYMBOLS	DRAWN BY	DATE	
MAJOR	Chen, Ya	18/03/05	
CRITICAL	CHECKED BY	DATE	
GENERAL TOLERANCES (UNLESS SPECIFIED)	BRAVE	18/03/05	TITLE
X. ±0.5	APPROVED BY	DATE	2.00mm WTB WAFER CONN.
.X ±0.25	BRAVE	18/03/05	T/H S/T TYPE
.XX ±0.15	UNITS		SIZE DWG. NO.
.XXX ±0.1	mm		A4
ANGLES ±2°	SCALE	SHEET NO.	REV PART NO.
	1:1	1 OF 1	E
			SEE NOTES